

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Canceled).

Claim 2 (Currently Amended): A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a ~~conductor~~ wiring layer formed on one surface thereof, the process comprising:

a first step to form ~~forming~~ a via hole in the base material having the ~~conductor~~ wiring layer by performing laser irradiation at least from the other surface side of the base material;

a second step to deposit a first electroplating by using the wiring layer as an electrode until the core material protruding from the inner wall surface of the via hole is covered;

a third step to form ~~forming~~ an electroless plating layer in close contact with an inner wall surface of the via hole and without contacting the core material ~~after deposition of a plating until the core material exposed on the inner wall surface of the via hole is covered by using the conductor layer as an electrode; and~~

a fourth step to deposit ~~depositing~~ a second electroplating ~~plating again~~ by using the conductor layer as an electrode to cover the electroless plating layer ~~to thereby form a conductor part in the via hole,~~

wherein three layers in order from a wiring-layer side: the first electroplating layer; the electroless plating layer; and the second electroplating layer, are stacked in the via hole to thereby form a conductor part.

Claim 3 (Currently Amended): A process for producing an electronic component according to Claim 2, wherein a laser beam is applied onto the base material with a power of

the laser beam adjusted in view of a difference in melting temperature between resin forming the base material and the core material such that the core material is ~~caused to~~ protrude from the inner wall surface of the via hole, ~~through laser irradiation~~ to thereby form an anchor structure with respect to the conductor part.

Claim 4 (Canceled).

Claim 5 (Currently Amended): A process for producing an electronic component according to any one of claims 2 ~~through 4~~ and 3, wherein the core material is formed of glass cloth.

Claims 6-13 (Canceled).